

# 2SC2590

## Silicon NPN epitaxial planar type

For low-frequency power amplification

Complementary to 2SA1110

### ■ Features

- Excellent current  $I_C$  characteristics of forward current transfer ratio  $h_{FE}$  vs. collector
- High transition frequency  $f_T$
- A complementary pair with 2SA1110, is optimum for the driver-stage of a 40 W to 60 W output amplifier
- TO-126B package which requires no insulation plate for installation to the heat sink

### ■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	$V_{CBO}$	120	V
Collector to emitter voltage	$V_{CEO}$	120	V
Emitter to base voltage	$V_{EBO}$	5	V
Peak collector current	$I_{CP}$	1	A
Collector current	$I_C$	0.5	A
Collector power dissipation *	$P_C$	1.2	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

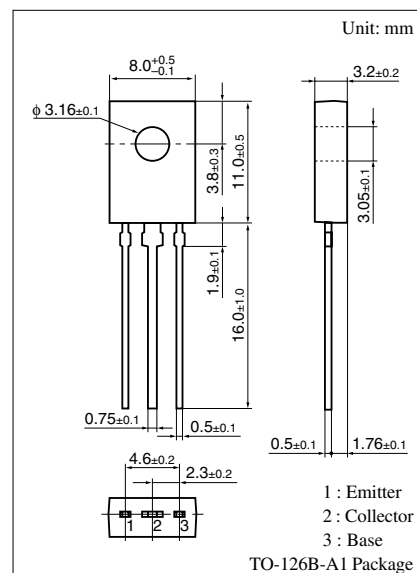
Note) \*: Without heat sink

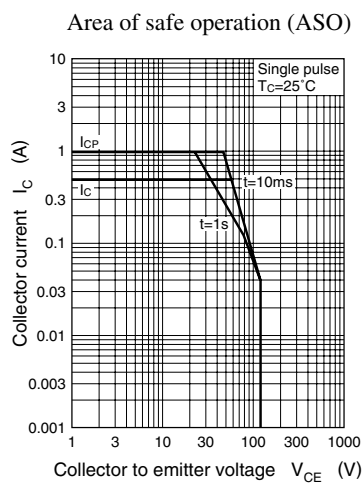
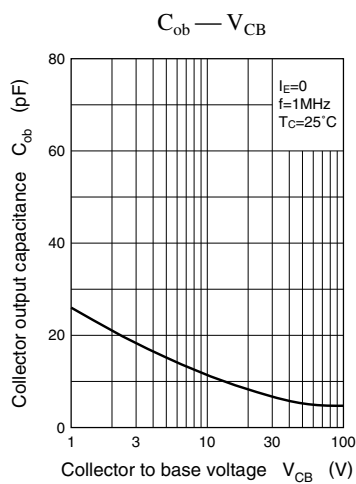
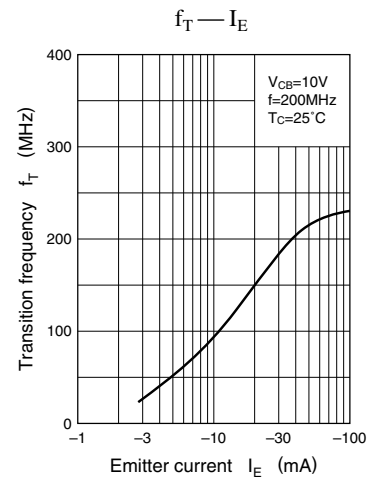
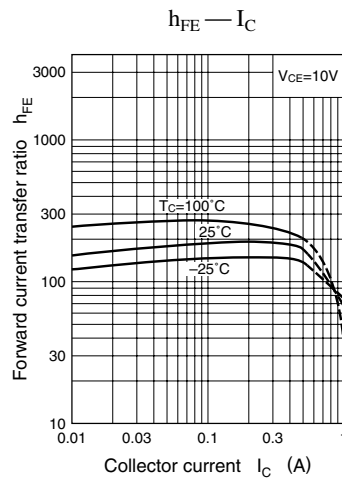
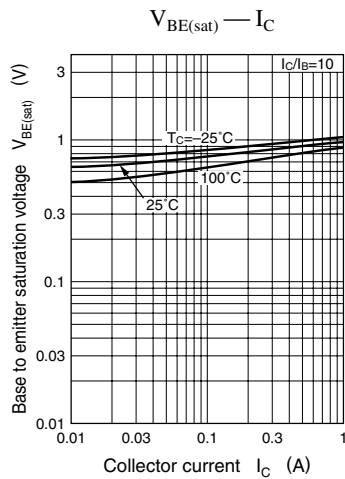
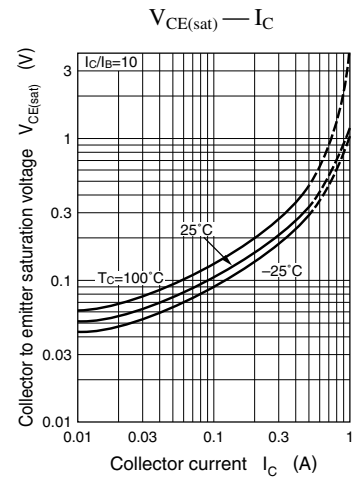
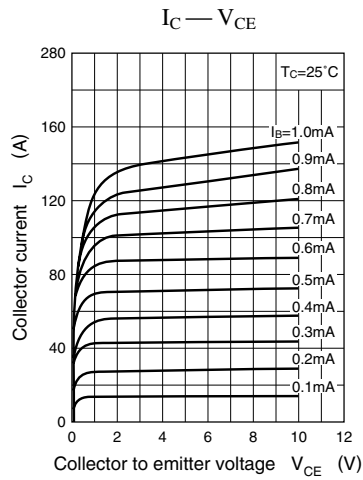
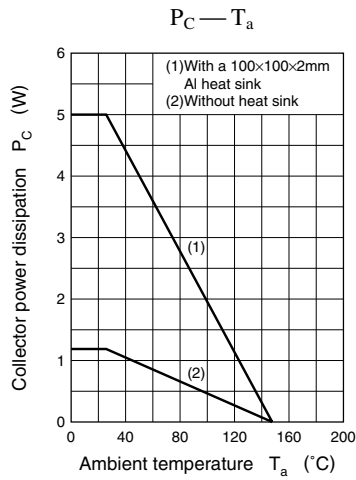
### ■ Electrical Characteristics $T_C = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector to emitter voltage	$V_{CEO}$	$I_C = 100\ \mu\text{A}$ , $I_B = 0$	120			V
Emitter to base voltage	$V_{EBO}$	$I_E = 10\ \mu\text{A}$ , $I_C = 0$	5			V
Forward current transfer ratio	$h_{FE1}$ *	$V_{CE} = 10\ \text{V}$ , $I_C = 150\ \text{mA}$	90		220	
	$h_{FE2}$	$V_{CE} = 5\ \text{V}$ , $I_C = 500\ \text{mA}$	65	100		
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 300\ \text{mA}$ , $I_B = 30\ \text{mA}$			1	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = 300\ \text{mA}$ , $I_B = 30\ \text{mA}$			1.2	V
Transition frequency	$f_T$	$V_{CB} = 10\ \text{V}$ , $I_E = -50\ \text{mA}$ , $f = 200\ \text{MHz}$		200		MHz
Collector output capacitance	$C_{ob}$	$V_{CB} = 10\ \text{V}$ , $I_E = 0$ , $f = 1\ \text{MHz}$		11	20	pF

Note) \*: Rank classification

Rank	Q	R
$h_{FE1}$	90 to 155	130 to 220





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